L	Hits	Search Text	DB	mina at any
Number	11105	Search Text	DB	Time stamp
1	2539907	semiconductor die chip ic (integrated adj	USPAT;	2004/06/28
-		circuit) dice	US-PGPUB;	06:20
		3234257 4255	EPO; JPO;	00.20
			DERWENT;	
			IBM TDB	•
2	687469	bump ball bga flipchip (flip adj chip)	USPAT;	2004/06/28
_		and aga and the comp	US-PGPUB;	06:21
			EPO; JPO;	00.21
}			DERWENT;	
			IBM TDB	
3	504975	disconnected disconnect disconnecting	USPAT;	2004/06/28
	1	dummy inactive nonelectrical (non adj	US-PGPUB;	06:25
		(electrical electrically connecting	EPO; JPO;	
		connected connect function functioning	DERWENT;	
		functioned))	IBM TDB	
4	3988	(bump ball bga flipchip (flip adj chip))	USPAT;	2004/06/28
		with (disconnected disconnect	US-PGPUB;	06:25
		disconnecting dummy inactive	EPO; JPO;	
		nonelectrical (non adj (electrical	DERWENT;	
		electrically connecting connected connect	IBM_TDB	
_		function functioning functioned)))	_	
5	905	(semiconductor die chip ic (integrated	USPAT;	2004/06/28
		adj circuit) dice) same ((bump ball bga	US-PGPUB;	06:26
		flipchip (flip adj chip)) with	EPO; JPO;	
		(disconnected disconnecting	DERWENT;	
		dummy inactive nonelectrical (non adj	IBM_TDB	
		(electrical electrically connecting		
		connected connect function functioning		
6	206	functioned))))		2004/05/00
0	∠06		USPAT;	2004/06/28
		((semiconductor die chip ic (integrated adj circuit) dice) same ((bump ball bga	US-PGPUB;	06:27
	·	flipchip (flip adj chip)) with	EPO; JPO; DERWENT;	
		(disconnected disconnect disconnecting	IBM TDB	
		dummy inactive nonelectrical (non adj	ממד_זיים	
		(electrical electrically connecting		
		connected connect function functioning		
		functioned)))))		